

## REMARKS

Favorable reconsideration of this application is respectfully requested.

Claims 1, 3, 5, 6, 9-12, 14, 17, 19-21 and 25-28 are present in this application, claims 25-28 being added by way of the present amendment.

Claims 12 and 21 have been rewritten in independent form by entry of the previous amendment, and claim 12 has been further amended in this paper to clarify the components of the clamp. Claims 12 and 21 are believed to be in condition for allowance. Claims 25-28 dependent from claim 21 are also believed to be in condition for allowance. The remaining claims are believed to be in condition for allowance for the reasons set forth in the prior response.

It is respectfully submitted that the present application is in condition for allowance and a favorable decision to that effect is respectfully requested.

Respectfully submitted,  
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IN THE CLAIMS

Please amend the claims as follows:

12. (Twice Amended) A worktable device for a semiconductor process, comprising:
- a worktable having a main surface for supporting a target substrate and a sub-surface disposed around said main surface;
    - a cooling mechanism disposed in said worktable and configured to supply cold to the main surface and the sub-surface;
    - a focus ring placed on the sub-surface and configured to surround the target substrate on the main surface;
    - a heat transfer medium interposed between the sub-surface and said focus ring, said heat transfer medium being so disposed as to improve thermal conductivity between the sub-surface and said focus ring to be higher than in a case with no thermal transfer medium;
    - a clamp configured to press said focus ring against the sub-surface;
  - wherein said clamp comprises a clamp frame having a contact portion which comes into contact with said focus ring from above, [and] an extending portion extending downward from the contact portion along a side portion of said worktable[;], and an outer cover substantially made of heat-resistant synthetic resin and configured to cover said clamp frame, and
  - wherein said cooling mechanism maintains said target substrate and the focus ring at substantially the same temperature.

25-28. (New)